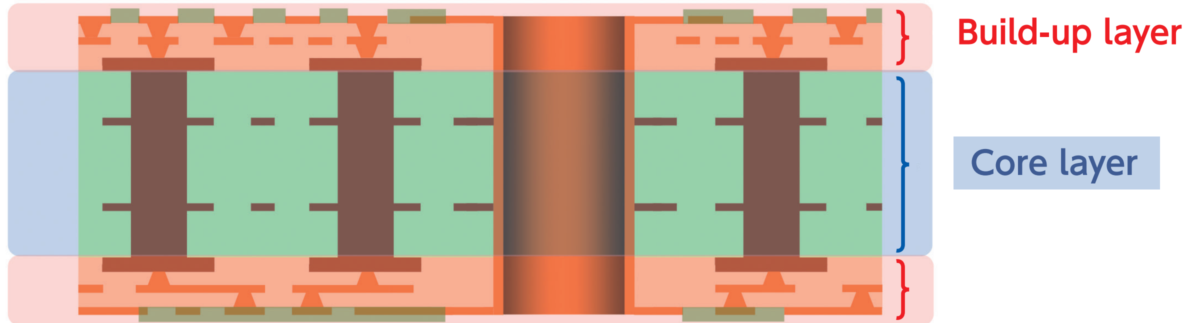
Acid copper plating additive for large-diameter via holes

TOP LUCINA GAP

SAP・MSAP

- For core layers to achieve high through-hole filling performance
- Excellent in filling performance for large-diameter via holes
- Regardless of pattern size and density, uniform thickness comes available



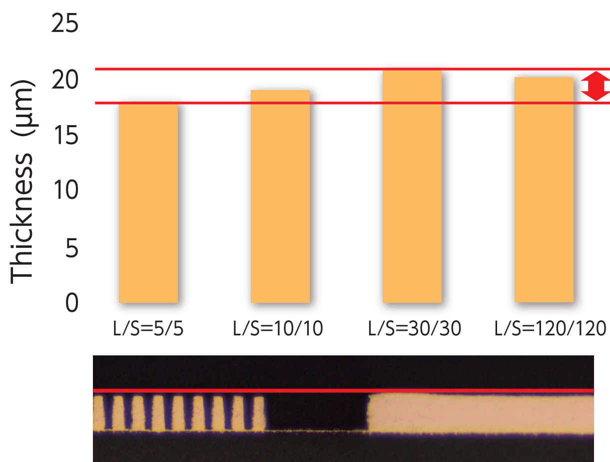
For large-diameter via

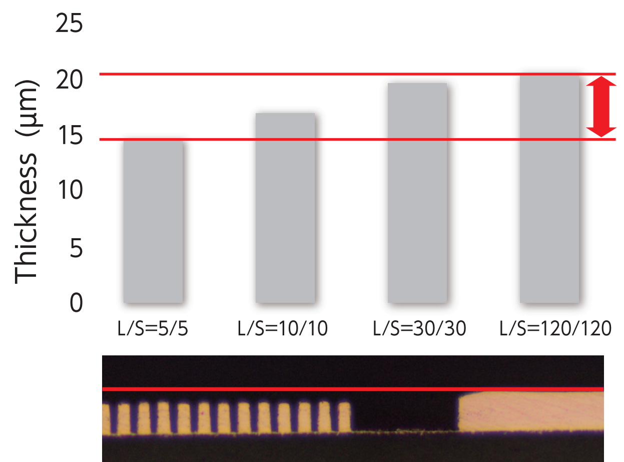
Via diameter／depth (µm)	
100/100	150/100

For through-hole filling

Via diameter (µm)		
55	75	95

Reduce thickness variation, freely draw fine patterns





Surface thickness 18 µm